506729310 06/23/2021

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JIANFENG SHAN	06/18/2021

RECEIVING PARTY DATA

CHONGQING HKC OPTOELECTRONICS TECHNOLOGY CO., LTD.	
NO. 1 SHIJING RD., JIESHI, BANAN DISTRICT	
CHONGQING	
CHINA	
HKC CORPORATION LIMITED	
5TH AND 7TH FLOOR OF FACTORY BUILDING 1, JIUZHOU YANGGUANG, FACTORY BUILDINGS 1, 2, 3 OF HKC INDUSTRIAL PARK	
PRIVATELY OPERATED INDUSTRIAL PARK, SHUITIAN VILLAGE, SHIYAN SUB-DISTRICT, BAOAN DISTRICT	
SHENZHEN	
CHINA	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17417392

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	HKC182199US1
NAME OF SUBMITTER:	RAYMOND J. CHEW
SIGNATURE: /Raymond J. Chew/	
DATE SIGNED:	06/23/2021

PATENT REEL: 056627 FRAME: 0028

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Total Attachments: 2

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PATENT REEL: 056627 FRAME: 0029

ASSIGNMENT OF APPLICATION

I/We, <u>SHAN</u>, <u>Jianfeng</u> whose residence and post office address are as stated below next to my/our name, hereafter referred to as applicant, have invented certain new and useful improvements in

	DRIVING METHOD AND SYSTEM OF DISPLAY PANEL, AND DIS	PLAY DEVICE
	(a PCT/CN2020/078415 to enter US national stage)	
	for which an application for a United States Patent was filed on	
Seri	al No	
\boxtimes	for which an application for a United States Patent was executed on	June 18, 2021
and		

Whereas, CHONGQING HKC OPTOELECTRONICS TECHNOLOGY CO., LTD., a corporation of CHINA herein referred to "assignee" whose mailing address is No. 1 Shijing Rd., Jieshi, Banan District, Chongqing, China and HKC CORPORATION LIMITED, a corporation of CHINA herein referred to "assignee" whose mailing address is 5th And 7th Floor Of Factory Building 1, Jiuzhou Yangguang, Factory Buildings 1, 2, 3 Of HKC Industrial Park, Privately Operated Industrial Park, Shuitian Village, Shiyan Sub-district, Baoan District, Shenzhen, Guangdong, China, are desirous of acquiring the entire right, title and interest in the same;

Now, therefore, in consideration of the sum of one dollar (\$1.00), the receipt whereof is acknowledged, and other good and valuable consideration, We/I, the applicant, by these presents do sell, assign and transfer unto said assignee the full and exclusive right to the said invention in the United States and the entire right, title and interest in and to any and all Patents which be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

Executed on	June 18, 2021	
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PATENT REEL: 056627 FRAME: 0030

Docket: HKC182199US1

Name: SHAN, Jianfeng

RECORDED: 06/23/2021

Address: 5th and 7th Floor of Factory Building 1, Jiuzhou

Yangguang, Factory Buildings 1, 2, 3 of HKC Industrial

Park, Privately Operated Industrial Park, Shuitian

Village, Shiyan Sub-district, Baoan District

Shenzhen City, Guangdong, China

PATENT

REEL: 056627 FRAME: 0031